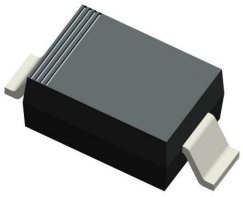
Technical Data
Data Sheet N1449, Rev. B

RoHS HF

BZT52C2V4S-BZT52C43S
ZENER DIODES



SOD-323

Features

- Planar Die Construction
- 200mW Power Dissipation
- General purpose, medium current
- Ideally suited for automated assembly processes
- Available in lead free version
- This is a Halogen Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Schematic & Pin Configuration

Mechanical Characteristics

- Case: SOD-323, Molded plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.04 grams(approx)

Maximum Ratings @T_A=25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Forward Voltage (Note 2) @ I_F = 10mA	V_F	0.9	V
Power Dissipation (Note 1)	P_D	200	mW
Thermal Resistance from Junction to Ambient	$R_{\Theta JA}$	625	°C/W
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C

Ordering Information

Device	Package	Shipping
BZT52C2V4S-BZT52C43S	SOD-323	3000pcs / reel
BZT52C2V4STR-BZT52C43STR	SOD-323	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

WX = Marking Code

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Electrical Characteristics @T_A=25°C unless otherwise specified

TYPE	Marking	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current (Note 2)		Typical Temperature Coefficient @I_{ZTC} mV/°C		Test Current I_{ZTC}
		V_Z@I_{ZT}			I_{ZT}	Z_{ZT}@I_{ZT}	Z_{ZK}@I_{ZK}	I_{ZK}	I_R	V_R			
		Nom(V)	Min(V)	Max(V)	(mA)	Ω		(mA)	μA	V	Min	Max	mA
BZT52C2V4S	WX	2.4	2.20	2.60	5	100	600	1.0	50	1.0	-3.5	0	5
BZT52C2V7S	WI	2.7	2.5	2.9	5	100	600	1.0	20	1.0	-3.5	0	5
BZT52C3V0S	W2	3.0	2.8	3.2	5	95	600	1.0	10	1.0	-3.5	0	5
BZT52C3V3S	W8	3.3	3.1	3.5	5	95	600	1.0	5	1.0	-3.5	0	5
BZT52C3V6S	W4	3.6	3.4	3.8	5	90	600	1.0	5	1.0	-3.5	0	5
BZT52C3V9S	W5	3.9	3.7	4.1	5	90	600	1.0	3	1.0	-3.5	0	5
BZT52C4V3S	W6	4.3	4.0	4.6	5	90	600	1.0	3	1.0	-3.5	0	5
BZT52C4V7S	W7	4.7	4.4	5.0	5	80	500	1.0	3	2.0	-3.5	0.2	5
BZT52C5V1S	W8	5.1	4.8	5.4	5	60	480	1.0	2	2.0	-2.7	1.2	5
BZT52C5V6S	W9	5.6	5.2	6.0	5	40	400	1.0	1	2.0	-2	2.5	5
BZT52C6V2S	WA	6.2	5.8	6.6	5	10	150	1.0	3	4.0	0.4	3.7	5
BZT52C6V8S	WB	6.8	6.4	7.2	5	15	80	1.0	2	4.0	1.2	4.5	5
BZT52C7V5S	WC	7.5	7.0	7.9	5	15	80	1.0	1	5.0	2.5	5.3	5
BZT52C8V2S	WD	8.2	7.7	8.7	5	15	80	1.0	0.7	5.0	3.2	6.2	5
BZT52C9V1S	WE	9.1	8.5	9.6	5	15	100	1.0	0.5	6.0	3.8	7.0	5
BZT52C10S	WF	10	9.4	10.6	5	20	150	1.0	0.2	7.0	4.5	8.0	5
BZT52C11S	WG	11	10.4	11.6	5	20	150	1.0	0.1	8.0	5.4	9.0	5
BZT52C12S	WH	12	11.4	12.7	5	25	150	1.0	0.1	8.0	6.0	10.0	5
BZT52C13S	WI	13	12.4	14.1	5	30	170	1.0	0.1	8.0	7.0	11.0	5
BZT52C15S	WJ	15	13.8	15.6	5	30	200	1.0	0.1	10.5	9.2	13	5
BZT52C16S	WK	16	15.3	17.1	5	40	200	1.0	0.1	11.2	10.4	14	5
BZT52C18S	WL	18	16.8	19.1	5	45	225	1.0	0.1	12.6	12.4	16	5
BZT52C20S	WM	20	18.8	21.2	5	55	225	1.0	0.1	14.0	14.4	18.0	5
BZT52C22S	WN	22	20.8	23.3	5	55	250	1.0	0.1	15.4	16.4	20.0	5
BZT52C24S	WO	24	22.8	25.6	5	70	250	1.0	0.1	16.8	18.4	22.0	5
BZT52C27S	WP	27	25.1	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3	2
BZT52C30S	WQ	30	28.0	32.0	2	80	300	0.5	0.1	21.0	24.4	29.4	2
BZT52C33S	WR	33	31.0	35.0	2	80	325	0.5	0.1	23.1	27.4	33.4	2
BZT52C36S	WS	36	34.0	38.0	2	90	350	0.5	0.1	25.2	30.4	37.4	2
BZT52C39S	WT	39	37.0	41.0	2	130	350	0.5	0.1	27.3	33.4	41.2	2
BZT52C43S	WU	43	40.0	46.0	2	100	700	1	0.1	32	10	12	5

Notes: 1. Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm2 .
2. Short duration test pulse used to minimize self-heating effect.
3. f = 1kHz.

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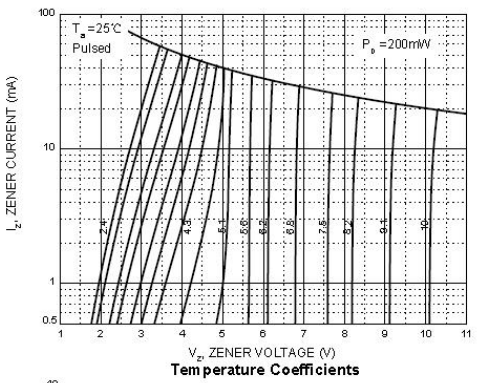
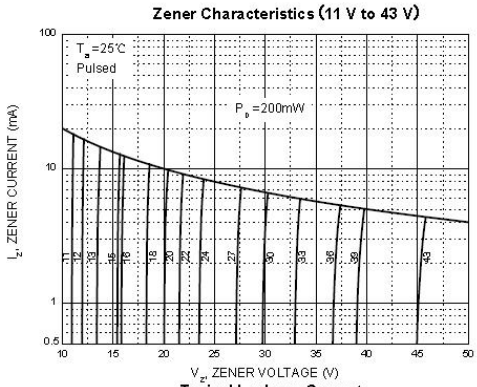
Ratings and Characteristics Curves

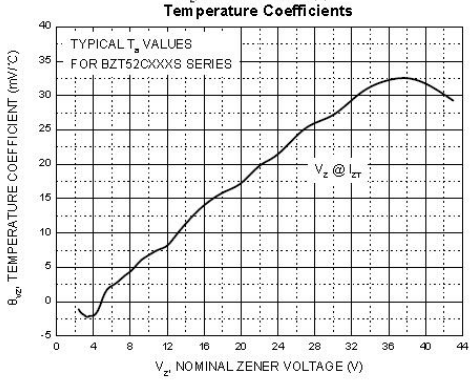
Zener Characteristics (V_z Up to 10 V)



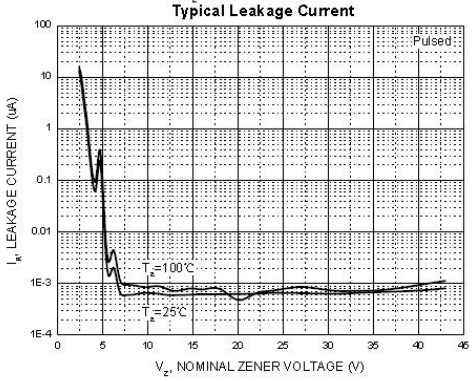
Zener Characteristics (11 V to 43 V)



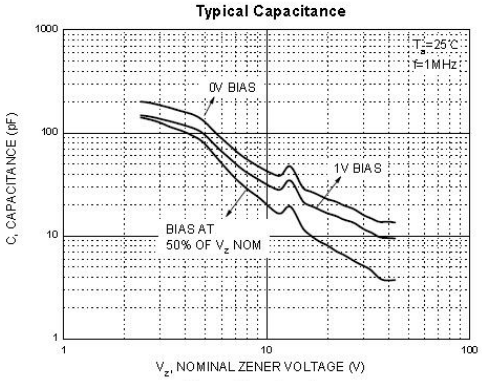
Temperature Coefficients



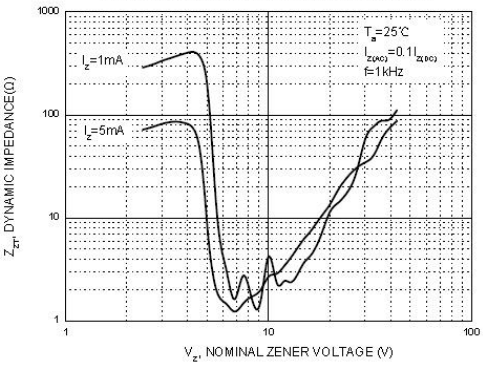
Typical Leakage Current



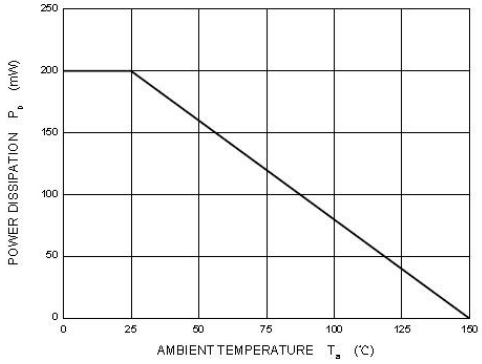
Typical Capacitance



Effect of Zener Voltage on Zener Impedance



Power Derating Curve



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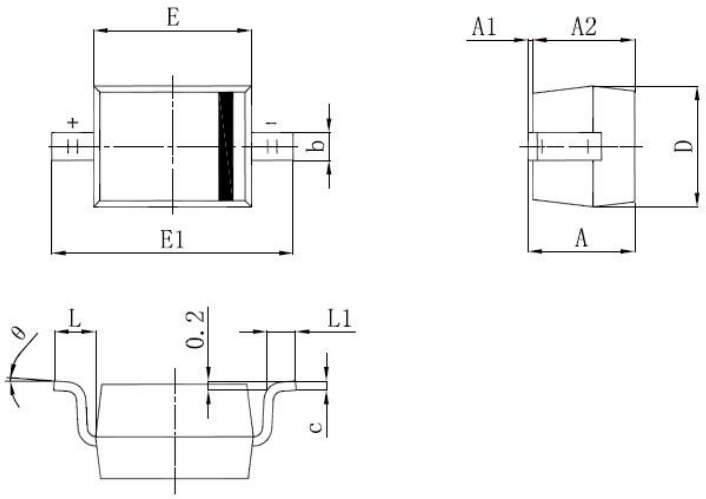
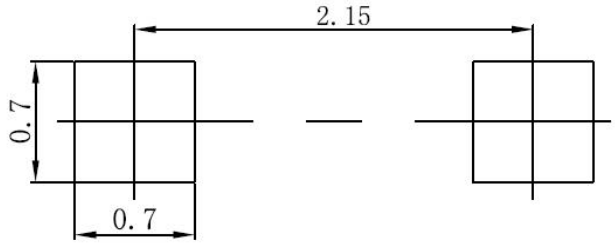
Mechanical Dimensions SOD-323



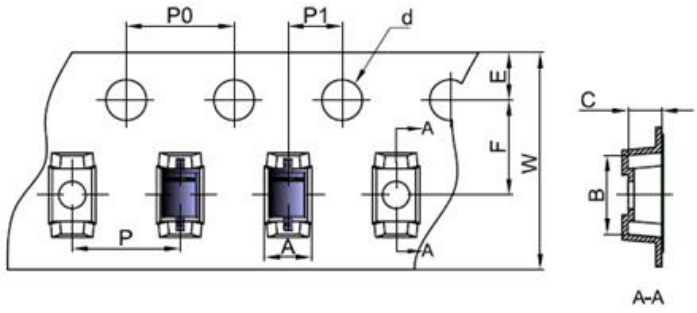
SYMBOL	Millimeters		Inches	
	MIN.	MAX.	MIN.	MAX.
A	-	1.000	-	0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.500	2.700	0.098	0.106
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

SOD-323 Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

Carrier Tape Specification SOD-323



SYMBOL	Millimeters	
	Min.	Max.
B	2.85	2.95
C	1.20	1.30
d	1.40	1.60
E	1.65	1.85
F	3.40	3.60
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
W	7.90	8.30

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